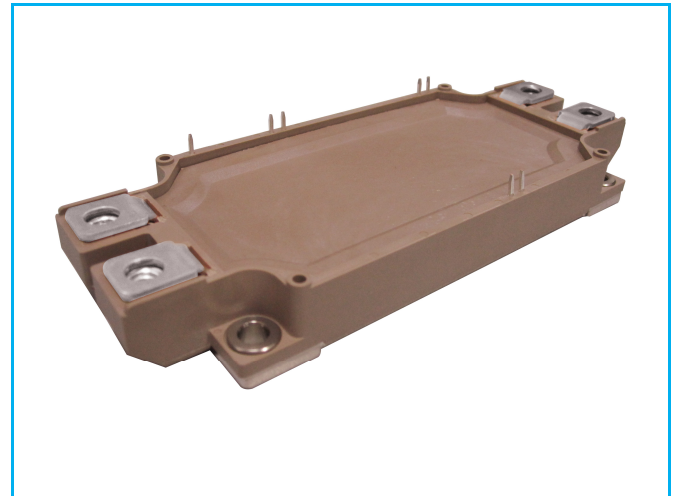


PRODUCT FEATURES

- High short circuit capability, self limiting short circuit current
- IGBT CHIP(Highly rugged SPT+ design)
- $V_{CE(sat)}$ with positive temperature coefficient
- Ultra Low Loss, High Ruggedness
- Free wheeling diodes with fast and soft reverse recovery
- Temperature sense included



APPLICATIONS

- AC motor control
- Motion/servo control
- Inverter and power supplies
- Photovoltaic/Fuel cell

IGBT-inverter

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | | Values | Unit |
|-----------|-----------------------------------|---------------------------|----------|------|
| V_{CES} | Collector Emitter Voltage | $T_J = 25^\circ\text{C}$ | 1700 | V |
| V_{GES} | Gate Emitter Voltage | | ± 20 | |
| I_C | DC Collector Current | $T_C = 25^\circ\text{C}$ | 670 | A |
| | | $T_C = 100^\circ\text{C}$ | 450 | |
| I_{CM} | Repetitive Peak Collector Current | $t_p = 1\text{ms}$ | 900 | |
| P_{tot} | Power Dissipation Per IGBT | | 2700 | W |

Diode-inverter

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | | Values | Unit |
|-------------|---------------------------------|---|--------|----------------------|
| V_{RRM} | Repetitive Reverse Voltage | $T_J = 25^\circ\text{C}$ | 1700 | V |
| $I_{F(AV)}$ | Average Forward Current | $T_C = 25^\circ\text{C}$ | 450 | A |
| I_{FRM} | Repetitive Peak Forward Current | $t_p = 1\text{ms}$ | 900 | |
| I^2t | | $T_J = 150^\circ\text{C}, t = 10\text{ms}, V_R = 0\text{V}$ | 25000 | A^2S |

MacMic Science & Technology Co., Ltd.

Add: #18, Hua Shan Zhong Lu, New District, Changzhou City, Jiangsu Province, P. R. of China

MMG450WB170B

IGBT-inverter

ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | | Min. | Typ. | Max. | Unit | |
|---------------|--|---|---|-------------------------|-------|------|---------------|
| $V_{GE(th)}$ | Gate Emitter Threshold Voltage | | $V_{CE}=V_{GE}, I_C=18\text{mA}$ | 5.4 | 6.2 | 7.4 | V |
| $V_{CE(sat)}$ | Collector Emitter Saturation Voltage | chip | $I_C=450\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$ | | 2.25 | 2.6 | |
| | | | $I_C=450\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$ | | 2.6 | | |
| | terminal | $I_C=450\text{A}, V_{GE}=15\text{V}, T_J=25^\circ\text{C}$ | | 2.7 | 3.1 | | |
| | | $I_C=450\text{A}, V_{GE}=15\text{V}, T_J=150^\circ\text{C}$ | | 3.1 | | | |
| I_{CES} | Collector Leakage Current | | $V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$ | | 3 | mA | |
| | | | $V_{CE}=1700\text{V}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$ | | 20 | mA | |
| I_{GES} | Gate Leakage Current | | $V_{CE}=0\text{V}, V_{GE}=\pm 15\text{V}, T_J=25^\circ\text{C}$ | -500 | | 500 | nA |
| Q_g | Gate Charge | | $V_{CE}=900\text{V}, I_C=450\text{A}, V_{GE}=\pm 15\text{V}$ | | 3 | | μC |
| C_{ies} | Input Capacitance | | $V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$ | | 27.5 | | nF |
| C_{res} | Reverse Transfer Capacitance | | | | 1.6 | | nF |
| $t_{d(on)}$ | Turn on Delay Time | | $V_{CC}=900\text{V}, I_C=450\text{A}$ $R_G=3\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load | $T_J=25^\circ\text{C}$ | | 210 | ns |
| | | | | $T_J=150^\circ\text{C}$ | | 250 | ns |
| t_r | Rise Time | | | $T_J=25^\circ\text{C}$ | | 170 | ns |
| | | | | $T_J=150^\circ\text{C}$ | | 175 | ns |
| $t_{d(off)}$ | Turn off Delay Time | | $V_{CC}=900\text{V}, I_C=450\text{A}$ $R_G=3\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load | $T_J=25^\circ\text{C}$ | | 600 | ns |
| | | | | $T_J=150^\circ\text{C}$ | | 700 | ns |
| t_f | Fall Time | | | $T_J=25^\circ\text{C}$ | | 170 | ns |
| | | | | $T_J=150^\circ\text{C}$ | | 310 | ns |
| E_{on} | Turn on Energy | | $V_{CC}=900\text{V}, I_C=450\text{A}$ $R_G=3\Omega,$ $V_{GE}=\pm 15\text{V},$ Inductive Load | $T_J=25^\circ\text{C}$ | | 190 | mJ |
| | | | | $T_J=125^\circ\text{C}$ | | 240 | mJ |
| | | | | $T_J=150^\circ\text{C}$ | | 260 | mJ |
| E_{off} | Turn off Energy | | | $T_J=25^\circ\text{C}$ | | 101 | mJ |
| | | | | $T_J=125^\circ\text{C}$ | | 140 | mJ |
| | | | | $T_J=150^\circ\text{C}$ | | 150 | mJ |
| I_{SC} | Short Circuit Current | | $tpsc \leq 10\mu\text{s}, V_{GE}=15\text{V}$ $T_J=150^\circ\text{C}, V_{CC}=1000\text{V}$ | | 1440 | | A |
| R_{thJC} | Junction to Case Thermal Resistance (Per IGBT) | | | | 0.055 | | K/W |

Diode-inverter

ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | | Min. | Typ. | Max. | Unit | |
|-------------|---|----------|--|------|------|---------------|-----|
| V_F | Forward Voltage | chip | $I_F=450\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$ | | 1.65 | 2.2 | V |
| | | | $I_F=450\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$ | | 1.8 | | |
| | | terminal | $I_F=450\text{A}, V_{GE}=0\text{V}, T_J=25^\circ\text{C}$ | | 2.15 | 2.5 | |
| | | | $I_F=450\text{A}, V_{GE}=0\text{V}, T_J=150^\circ\text{C}$ | | 2.3 | | |
| t_{rr} | Reverse Recovery Time | | $I_F=450\text{A}, V_R=900\text{V}$ | | 1000 | ns | |
| I_{RRM} | Max. Reverse Recovery Current | | $dI_F/dt=-2500\text{A}/\mu\text{s}$ | | 370 | A | |
| Q_{RR} | Reverse Recovery Charge | | $T_J=150^\circ\text{C}$ | | 175 | μC | |
| E_{rec} | Reverse Recovery Energy | | | | 130 | mJ | |
| R_{thJCD} | Junction to Case Thermal Resistance (Per Diode) | | | | 0.1 | | K/W |

MMG450WB170B

NTC CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | Min. | Typ. | Max. | Unit |
|-------------|---|------|------|------|------------|
| R_{25} | Resistance $T_C=25^\circ\text{C}$ | | 5 | | K Ω |
| $B_{25/50}$ | $R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298.15 \text{ K}))]$ | | 3375 | | K |

MODULE CHARACTERISTICS ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter/Test Conditions | Values | Unit | |
|------------|-----------------------------|----------------------------|-------|----|
| T_{Jmax} | Max. Junction Temperature | 175 | °C | |
| T_{Jop} | Operating Temperature | -40~150 | | |
| T_{stg} | Storage Temperature | -40~125 | | |
| V_{isol} | Isolation Breakdown Voltage | AC, 50Hz(R.M.S), t=1minute | 4000 | V |
| CTI | Comparative Tracking Index | | > 225 | |
| Torque | to heatsink | Recommended (M5) | 2.5~5 | Nm |
| | to terminal | Recommended (M6) | 3~5 | Nm |
| Weight | | | 350 | g |

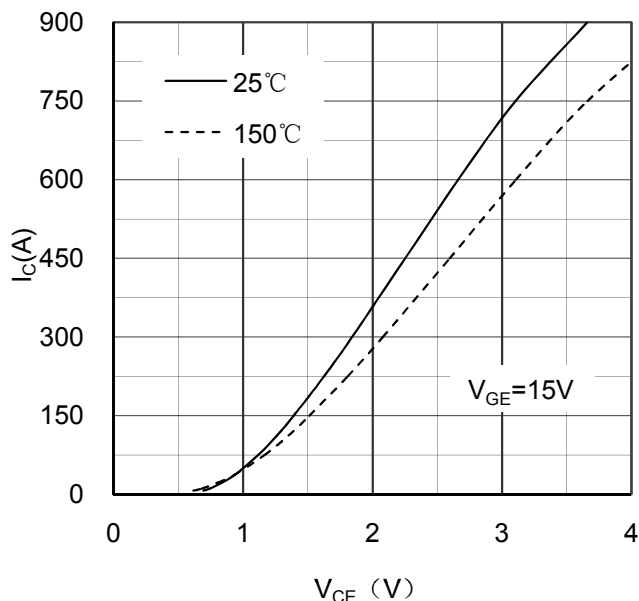


Figure 1. Typical Output Characteristics IGBT-inverter

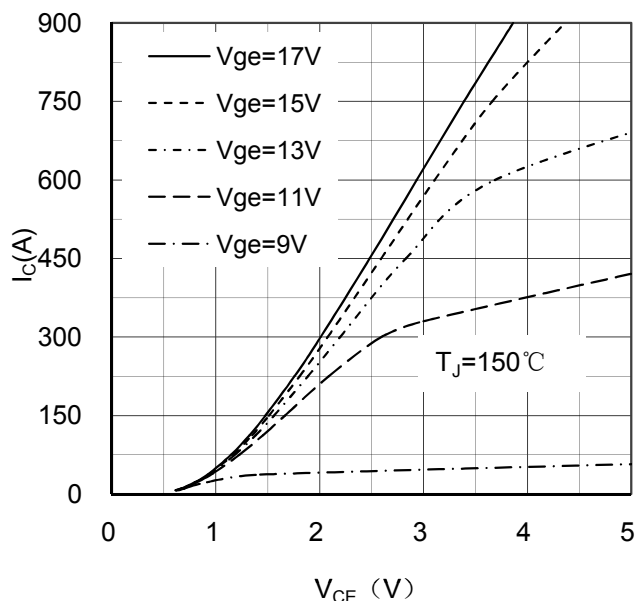


Figure 2. Typical Output Characteristics IGBT-inverter

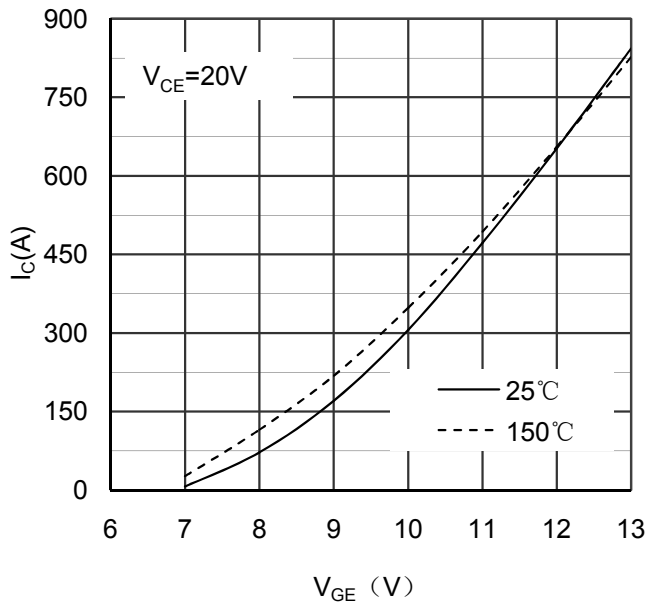


Figure 3. Typical Transfer characteristics IGBT-inverter

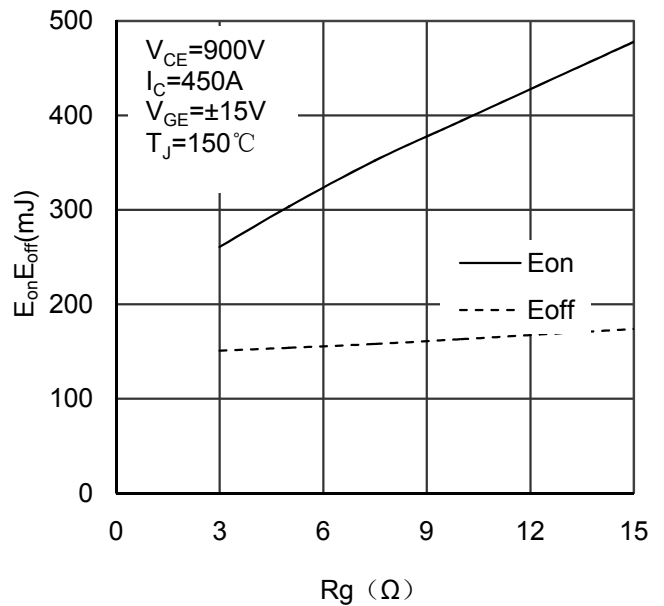


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

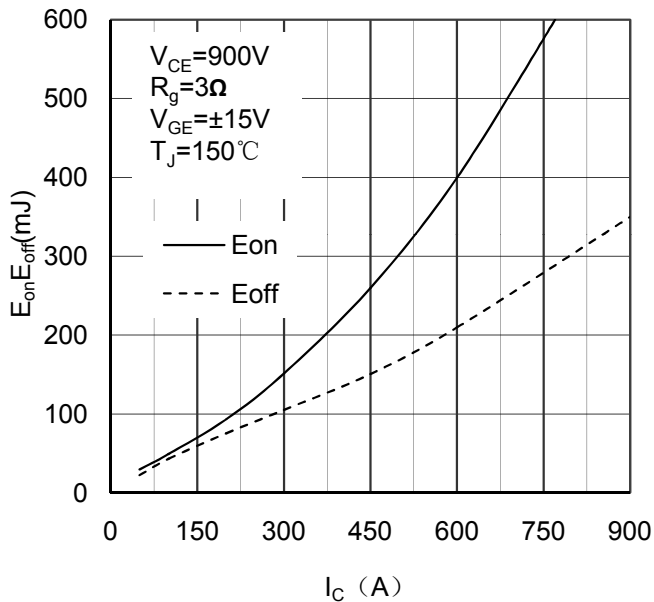


Figure 5. Switching Energy vs Collector Current IGBT-inverter

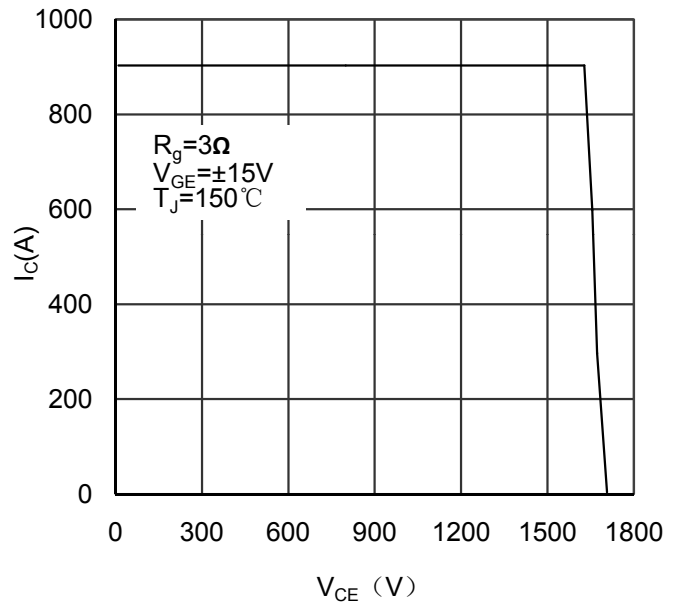


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

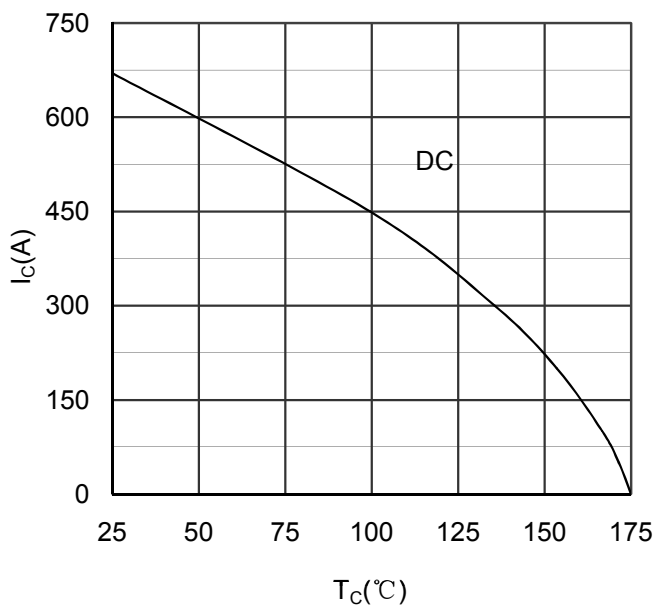


Figure 7. Collector Current vs Case temperature IGBT-inverter

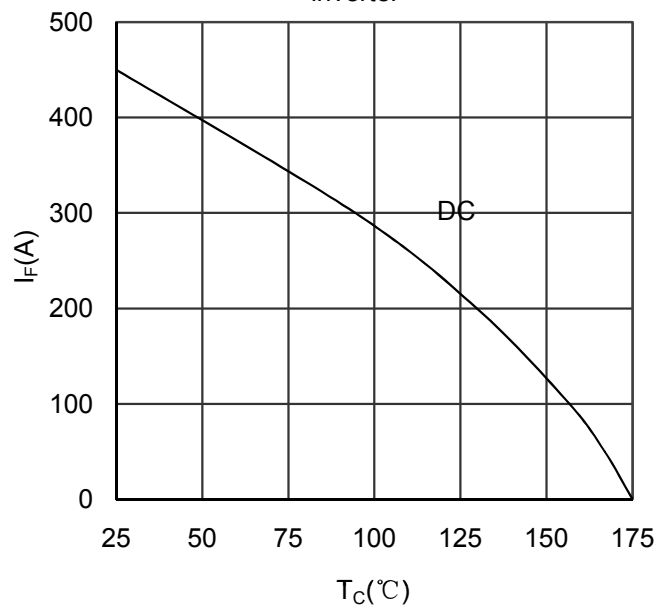


Figure 8. Forward current vs Case temperature Diode-inverter

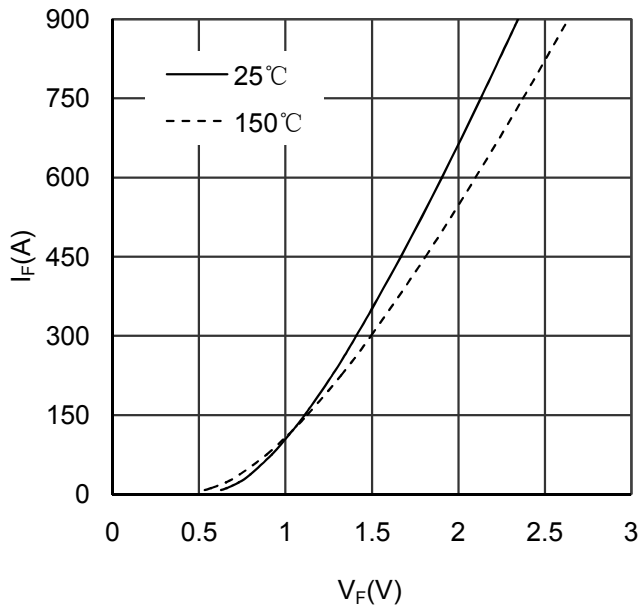


Figure 9. Diode Forward Characteristics Diode -inverter

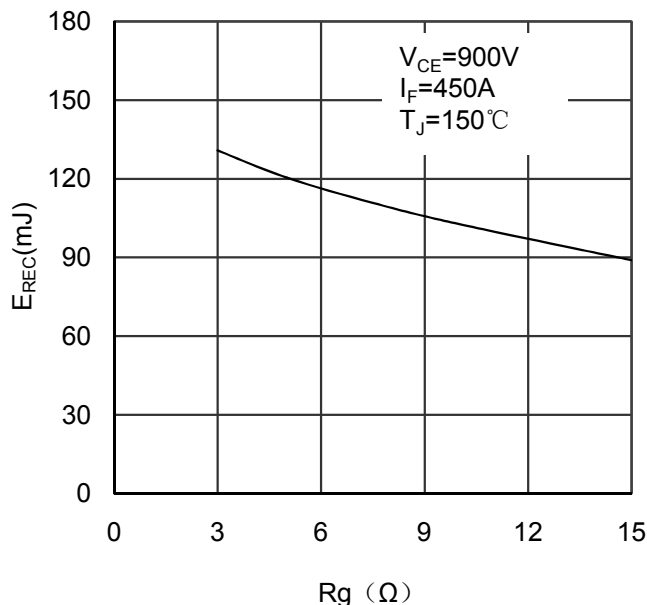


Figure 10. Switching Energy vs Gate Resistor Diode -inverter

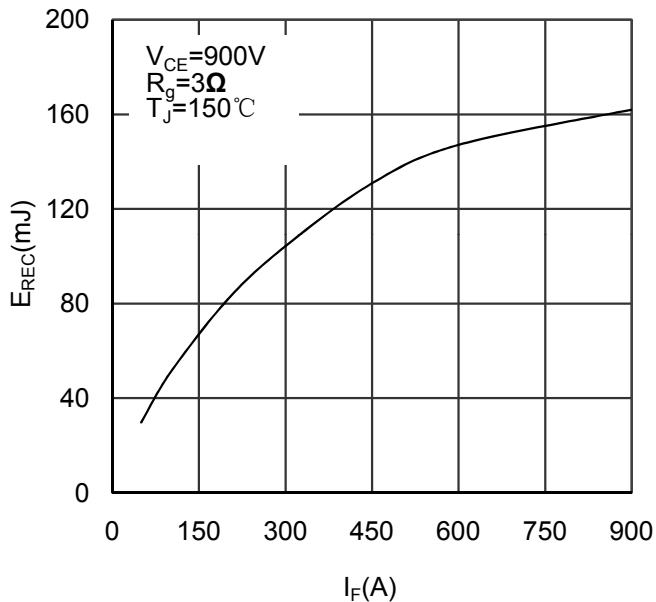


Figure 11. Switching Energy vs Forward Current Diode-inverter

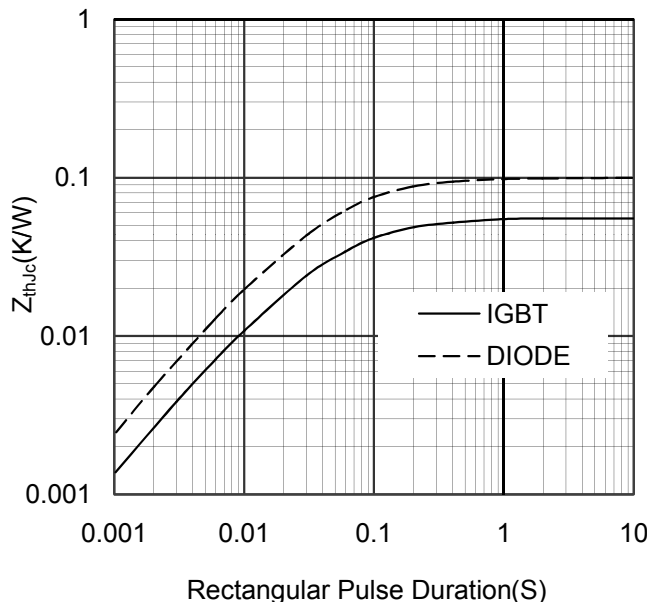


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

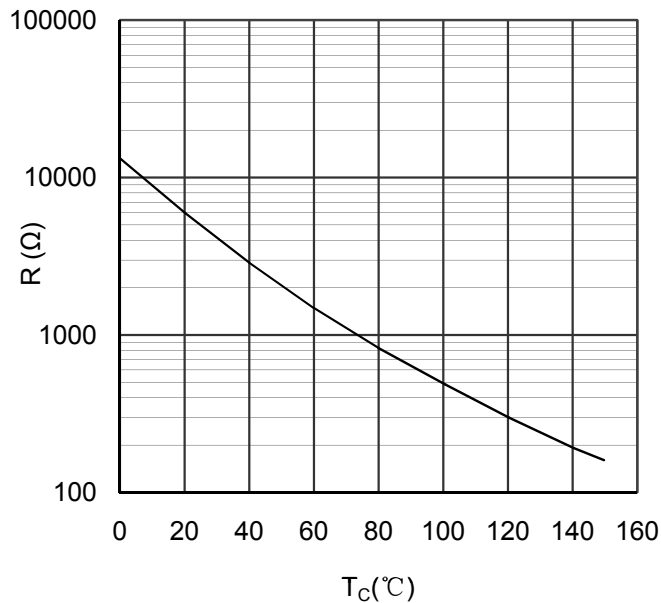


Figure 13. NTC Characteristics

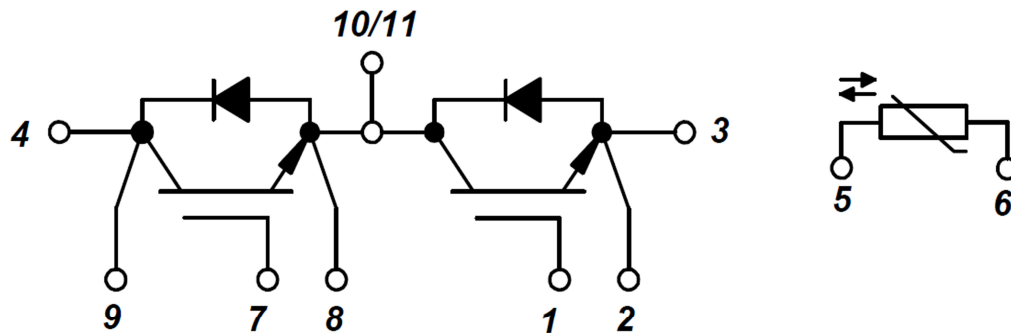


Figure 14. Circuit Diagram

